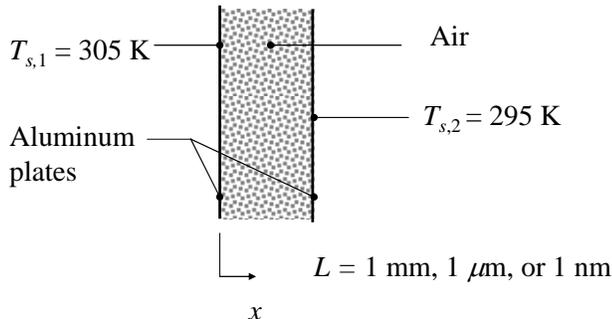


PROBLEM 3.173

KNOWN: Size and temperatures of parallel aluminum plates. Spacing between the plates. Air between the plates.

FIND: The conduction heat transfer through the air.

SCHEMATIC:



ASSUMPTIONS: (1) Ideal gas behavior.

PROPERTIES: Table A.4 ($T = 300 \text{ K}$): Air; $c_p = 1007 \text{ J/kg}\cdot\text{K}$, $k = 0.0263 \text{ W/m}\cdot\text{K}$. Figure 2.8: Air; $\mathcal{M} = 28.97 \text{ kg/kmol}$, $d = 0.372 \times 10^{-9} \text{ m}$.

ANALYSIS: For air, the ideal gas constant, specific heat at constant volume, and ratio of specific heats are:

$$R = \frac{\mathcal{R}}{\mathcal{M}} = \frac{8.315 \text{ kJ/kmol}\cdot\text{K}}{28.97 \text{ kg/kmol}} = 0.287 \frac{\text{kJ}}{\text{kg}\cdot\text{K}};$$

$$c_v = c_p - R = 1007 \frac{\text{kJ}}{\text{kg}\cdot\text{K}} - 0.287 \frac{\text{kJ}}{\text{kg}\cdot\text{K}} = 0.720 \frac{\text{kJ}}{\text{kg}\cdot\text{K}}; \quad \gamma = \frac{c_p}{c_v} = \frac{1.007}{0.720} = 1.399$$

From Equation 2.11 the mean free path of air is

$$\lambda_{\text{mfp}} = \frac{k_B T}{\sqrt{2} \pi d^2 p} = \frac{1.381 \times 10^{-23} \text{ J/K} \times 300 \text{ K}}{\sqrt{2} \pi (0.372 \times 10^{-9} \text{ m})^2 (1.0133 \times 10^5 \text{ N/m}^2)} = 66.5 \times 10^{-9} \text{ m} = 66.5 \text{ nm}$$

For $L = 1 \text{ mm}$,

$$R_{t,m-m} = \frac{L}{kA} = \frac{1 \times 10^{-3} \text{ m}}{0.0263 \text{ W/m}\cdot\text{K} \times 10 \times 10^{-3} \text{ m} \times 10 \times 10^{-3} \text{ m}} = 380.2 \text{ K/W}$$

$$R_{t,m-s} = \frac{\lambda_{\text{mfp}}}{kA} \left[\frac{2 - \alpha_t}{\alpha_t} \right] \left[\frac{9\gamma - 5}{\gamma + 1} \right] = \frac{66.5 \times 10^{-9} \text{ m}}{0.0263 \text{ W/m}\cdot\text{K} \times 100 \times 10^{-6} \text{ m}^2} \left[\frac{2 - 0.92}{0.92} \right] \left[\frac{9 \times 1.399 - 5}{1.399 + 1} \right]$$

$$= 0.09392 \text{ K/W}$$

Hence, the conduction heat rate is

Continued...

PROBLEM 3.173 (Cont.)

$$q = \frac{T_{s,1} - T_{s,2}}{(R_{t,m-m} + R_{t,m-s})} = \frac{305\text{K} - 295\text{K}}{(380.2 \text{ K/W} + 0.09392 \text{ K/W})} = 0.0263 \text{ W} \quad <$$

For $L = 1 \mu\text{m}$,

$$R_{t,m-m} = \frac{L}{kA} = \frac{1 \times 10^{-6} \text{ m}}{0.0263 \text{ W/m} \cdot \text{K} \times 10 \times 10^{-3} \text{ m} \times 10 \times 10^{-3} \text{ m}} = 0.3802 \text{ K/W}$$

$$R_{t,m-s} = 0.09392 \text{ K/W}$$

Hence, the conduction heat rate is

$$q = \frac{T_{s,1} - T_{s,2}}{(R_{t,m-m} + R_{t,m-s})} = \frac{305\text{K} - 295\text{K}}{(0.3802 \text{ K/W} + 0.09392 \text{ K/W})} = 21.09 \text{ W} \quad <$$

For $L = 10 \text{ nm}$,

$$R_{t,m-m} = \frac{L}{kA} = \frac{10 \times 10^{-9} \text{ m}}{0.0263 \text{ W/m} \cdot \text{K} \times 10 \times 10^{-3} \text{ m} \times 10 \times 10^{-3} \text{ m}} = 0.0038 \text{ K/W}$$

$$R_{t,m-s} = 0.09392 \text{ K/W}$$

Hence, the conduction heat rate is

$$q = \frac{T_{s,1} - T_{s,2}}{(R_{t,m-m} + R_{t,m-s})} = \frac{305\text{K} - 295\text{K}}{(0.0038 \text{ K/W} + 0.09392 \text{ K/W})} = 102.3 \text{ W} \quad <$$

COMMENT: If the molecule-surface collision resistance were to be neglected, the heat rates would be $q = 0.0263 \text{ W}$, 26.3 W , and 2632 W for the $L = 1 \text{ mm}$, $1 \text{ } \mu\text{m}$ and 10 nm plate spacings, respectively. Hence, molecule-surface collisions are negligible for large plate spacings, and dominant at small plate spacings.